



TS2100S

MICRO SURFACE MOUNT SCHOTTKY BRIDGE

VOLTAGE 100 Volts CURRENT 2 Amperes

FEATURES

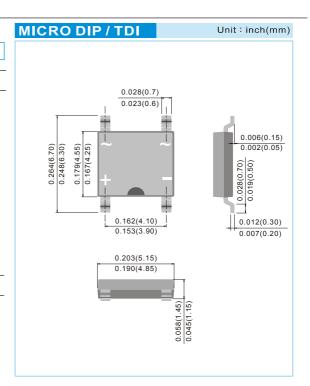
- Plastic package has Underwriters Laboratory Flammability Classification 94V-O.
 Flame Retardant Epoxy Molding Compound.
- Exceeds environmental standards of MIL-S-19500/228
- · Low power loss, high efficiency.
- · Low forwrd voltge, high current capability
- · High surge capacity.
- Super fast recovery times, high voltage.
- · Epitaxial chip construction.
- In compliance with EU RoHS 2002/95/EC directives

MECHANICAL DATA

- · Case: MDI Molded plastic
- Terminals: Lead solderable per MIL-STD-750, Method 2026
- Polarity: As marked.Standard packaging: AnyWeight: 0.090 grams.



ABSOLUTE MAXIMUM RATINGS (TA=25°C unless otherwise noted)



	1		
PARAMETER		TS2100S	UNITS
Maximum Peak Repetitve Reverse Voltage	V _{RRM}	100	V
Maximum RMS Reverse Voltage	V _{RMS}	70	٧
Maximum DC Blocking Voltage	V _R	100	V
Maximum Average Forward Current T c =50 °C	I _{F(AV)}	2	А
Non-Repetitive Peak Surge Current (Surge applied at rate Load conditions halfware, single phase, 60Hz)	FSM	50	Α
Typical Thermal Resistance, Junction to Ambient (Note1)	R _{eJA}	135	°C/W
Operating Junction Temperature and Storage Temperature Range	TJ,TSTG	-50 to +125	°C

NOTES:

1. Mounted on minimum pad layout(1cmX1cm FR-4 board).

June 17,2011-REV.01 PAGE . 1





TS2100S

ELECTRICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX.	UNIT
Reverse Current	l R	V _R =100V	-	-	4	μΑ
Reverse breakdown voltage	V(BR)R	I R=150μA	100	-	-	V
Forward Voltage	VF	IF=2A	-	770	840	mV
Typical Junction capacitance	Cı	VR=4V,f=1MHz	-	110	-	pF

RATING AND CHARACTERISTIC CURVES

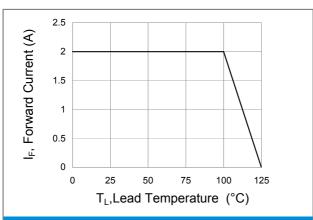


Fig.1 Forward Current Derating Curve

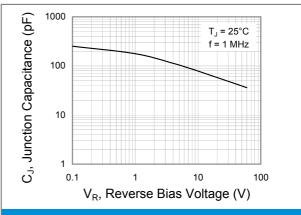
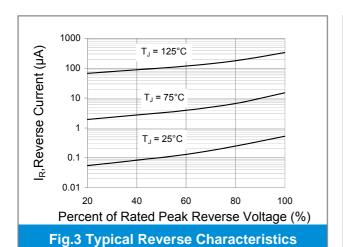
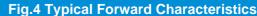
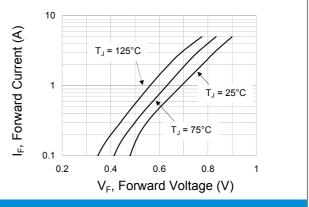


Fig.2 Typical Junction Capacitance







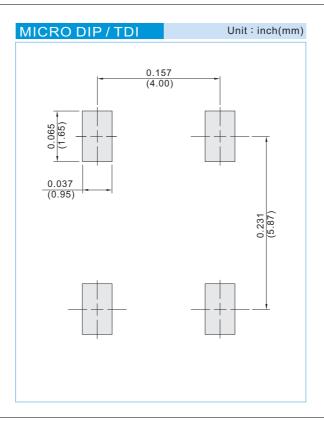
June 17,2011-REV.01





TS2100S

MOUNTING PAD LAYOUT



ORDER INFORMATION

Packing information

T/R - 4K per 13" plastic Reel

T/R - 1K per 7" plastic Reel

LEGAL STATEMENT

Copyright PanJit International, Inc 2011

The information presented in this document is believed to be accurate and reliable. The specifications and information herein are subject to change without notice. Pan Jit makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose. Pan Jit products are not authorized for use in life support devices or systems. Pan Jit does not convey any license under its patent rights or rights of others.

June 17,2011-REV.01 PAGE . 3



HALOGEN FREE PRODUCT DECLARATION

(Use green molding compound:ELER-8)

- 1. Pan Jit can produce halogen free product use molding compound for packing from Mar.2008 that contain Br<700 ppm,Cl<700ppm, Br+Cl<1000ppm,Sb2O3<100ppm.
- 2. If your company need halogen free product shall be note requirement green compound material on order for the halogen free product request.